

POM copolymer injection molding grade with reduced emissions especially for automotive interior application. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Emission according to VDA 275 < 2 mg/kg (natural grades) Emission according to VDA 275 < 5 mg/kg (colored grades)

ECO-B: Hostaform ECO-B is a POM-Copolymer with the same properties and performance as standard grades but produced with sustainability in mind. Using a mass-balance approach, biogenic feedstocks are used to offset the use of fossil-based raw materials and decrease greenhouse gas emissions. The process is audited and certified according to the ISCC Plus mass balance approach.

Product information

Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load	8 190 2.16	-	ISO 1133
Moulding shrinkage, parallel Moulding shrinkage, normal	2.0 1.9		ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Poisson's ratio [C]: Calculated	10 35 2600 2400 1200 220 220 6.5	MPa % MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA
Thermal properties Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Temperature of deflection under load, 0.45 MPa Coefficient of linear thermal expansion (CLTE), parallel Coefficient of linear thermal expansion (CLTE),		°C	ISO 11357-1/-3 ISO 75-1/-2 ISO 75-1/-2 ISO 11359-1/-2 ISO 11359-1/-2
normal Electrical properties Relative permittivity, 100Hz Relative permittivity, 1MHz Dissipation factor, 100Hz Dissipation factor, 1MHz	-	E-4 E-4	IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1

(+) **18816996168** Ponciplastics.com



HOSTAFORM[®] C 9021 XAP[®]2 ECO-B HOSTAFORM®

Volume resistivity Surface resistivity Electric strength Comparative tracking index		1E14	Ohm.m Ohm kV/mm	IEC 62631-3-1 IEC 62631-3-2 IEC 60243-1 IEC 60112
Physical/Other properties				
Humidity absorption, 2mm		0.2	%	Sim. to ISO 62
Water absorption, 2mm		0.65		Sim. to ISO 62
Density			kg/m ³	ISO 1183
			C C C C C C C C C C C C C C C C C C C	
Injection				
Drying Recommended		no		
Drying Temperature		100	°C	
Drying Time, Dehumidified Dryer		3 - 4		
Processing Moisture Content		≤0.2	%	
Melt Temperature Optimum		190		
Min. melt temperature		180		
Max. melt temperature		200		
Screw tangential speed		≤0.3		
Mold Temperature Optimum		100		
Min. mould temperature			°C	
Max. mould temperature		120	-	
Hold pressure range		60 - 120		
Back pressure		4	MPa	
Characteristics				
Processing	Injection Moulding			
Delivery form	Pellets			

Additives Special characteristics

Sustainability

Additional information

Injection molding

Preprocessing

Release agent

Low emissions Bio-Content

To achive low emission values pre drying using a recirculating air dryer (100 to 120 $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.





Melt temperature 180-190 °C Mould temperature 60-120 °C

Postprocessing

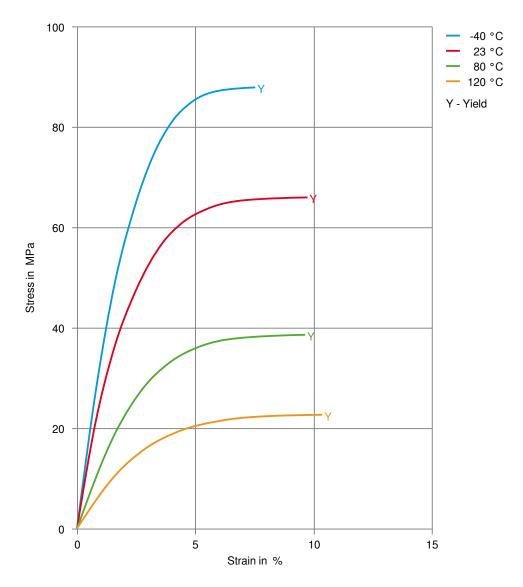
Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

recommended

Stress-strain

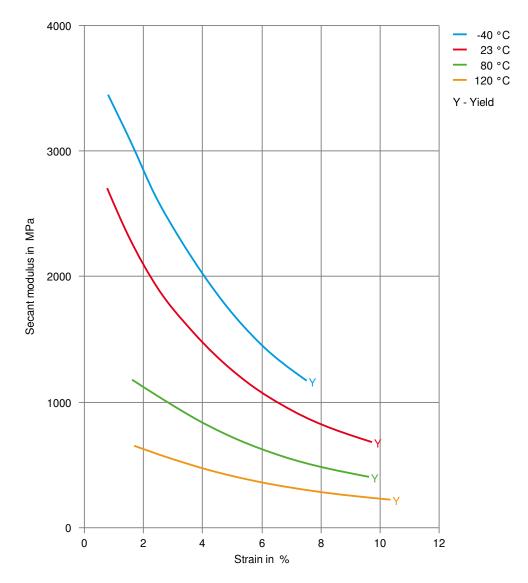


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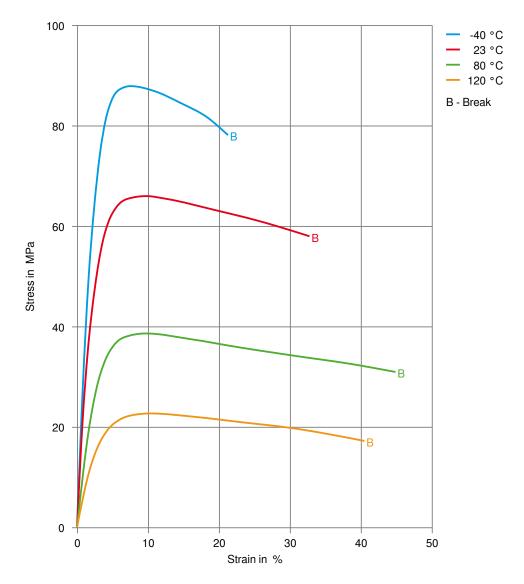
Secant modulus-strain







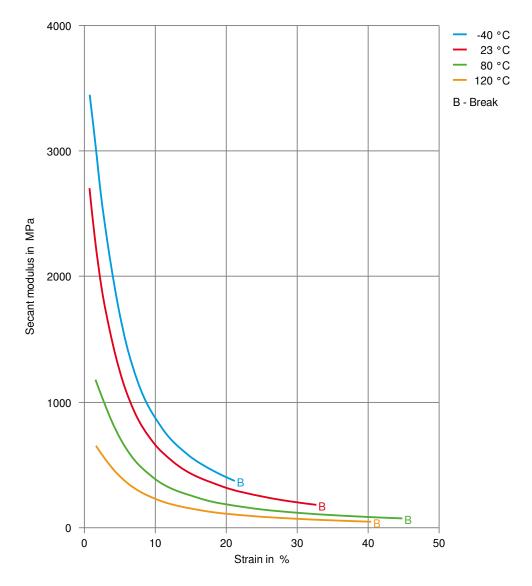
Stress-strain, 50mm/min







Secant modulus-strain, 50mm/min



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